• Low Input Bias Current 50 pA Typ	D OR N PACKAGE
 Low Input Noise Current 	(TOP VIEW)
0.01 pA/√Hz Typ	
 Low Total Harmonic Distortion 	
Low Supply Current 8 mA Typ	1IN – [] 2 13 [] 4IN – 1IN + [] 3 12 [] 4IN +
Gain Bandwidth 3 MHz Typ	V_{CC+} 4 11 V_{CC-}
 High Slew Rate 13 V/μs Typ 	2IN+[5 10] 3IN+
• Pin Compatible With the LM348	2IN-[] 6 9[] 3IN-
·	
description	

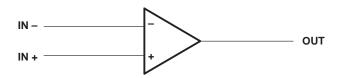
description

These devices are low-cost, high-speed, JFET-input operational amplifiers. They require low supply current yet maintain a large gain-bandwidth product and a fast slew rate. In addition, their matched high-voltage JFET inputs provide very low input bias and offset current.

The LF347 and LF347B can be used in applications such as high-speed integrators, digital-to-analog converters, sample-and-hold circuits, and many other circuits.

The LF347 and LF347B are characterized for operation from 0°C to 70°C.

symbol (each amplifier)



	Viemov	PACKAGE				
TA	V _{IO} max AT 25°C	SMALL OUTLINE (D)	PLASTIC DIP (N)			
0°C to 70°C	10 mV	LF347D	LF347N			
0010700	5 mV	LF347BD	LF347BN			

AVAILABLE OPTIONS

The D packages are available taped and reeled. Add R suffix to the device type (e.g., LF347DR).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC +}	
Supply voltage V _{CC}	
Differential input voltage, V _{ID}	±30 V
Input voltage, VI (see Note 1)	
Duration of output short circuit	unlimited
Continuous total power dissipation	See Dissipation Rating Table
Operating temperature range	0°C to 70°C
Storage temperature range	−65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

NOTE 1: Unless otherwise specified, the absolute maximum negative input voltage is equal to the negative power supply voltage.



LF347, LF347B JFET-INPUT QUAD OPERATIONAL AMPLIFIERS

SLOS013B - MARCH 1987 - REVISED AUGUST 1994

DISSIPATION RATING TABLE						
PACKAGE	$T_A \le 25^{\circ}C$	DERATING	DERATE	T _A = 70°C		
	POWER RATING	FACTOR	ABOVE T _A	POWER RATING		
D	608 mW	7.6 mW/°C	61°C	608 mW		
N	680 mW	N/A	N/A	680 mW		

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V _{CC +}	3.5	18	V
Supply voltage, V _{CC –}	-3.5	-18	V

electrical characteristics over operating free-air temperature range, $V_{CC\pm}$ = ±15 V (unless otherwise specified)

DADAMETED		TEST	_ +	+ LF347		LF347B			UNIT		
	PARAMETER	CONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT	
Vie	Input offect voltage	$V_{IC} = 0,$	25°C		5	10		3	5	mV	
VIO	Input offset voltage	$R_S = 10 k\Omega$	Full range			13			7	IIIV	
αΛΙΟ	Average temperature coefficient of input offset voltage	$V_{IC} = 0,$ R _S = 10 k Ω			18			18		μV/°C	
1	+	25°C			25	100		25	100	pА	
IO Input offset current [‡]		$V_{IC} = 0$	70°C			4			4	nA	
	Input bias current‡	+		25°C		50	200		50	200	pА
IB Int		AIC = 0	70°C			8			8	nA	
VICR	Common-mode input voltage range			±11	-12 to 15		±11	-12 to 15		V	
VOM	Maximum peak output voltage swing	RL = 10 kΩ		±12	±13.5		±12	±13.5		V	
A		$V_{O} = \pm 10 V_{,}$	25°C	25	100		50	100			
AVD Large-signal differential voltage		$R_L = 2 k\Omega$	Full range	15			25			V/mV	
r _i	Input resistance	T _A = 25°C			1012			1012		Ω	
CMRR	Common-mode rejection ratio	$R_{S} \le 2 k\Omega$		70	100		80	100		dB	
k _{SVR}	Supply-voltage rejection ratio	See Note 2		70	100		80	100		dB	
ICC	Supply current				8	11		8	11	mA	
	1 000 1 2000	-		-							

[†]Full range is 0°C to 70°C.

‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive. Pulse techniques must be used that will maintain the junction temperatures as close to the ambient temperature as possible.

NOTE 2: Supply-voltage rejection ratio is measured for both supply magnitudes increasing or decreasing simultaneously.

operating characteristics, V_{CC\pm} = ± 15 V

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V ₀₁ /V ₀₂	Crosstalk attentuation	f = 1 kHz		120		dB
SR	Slew rate		8	13		V/µs
B ₁	Unity-gain bandwidth			3		MHz
V _n	Equivalent input noise voltage	f = 1 kHz, $R_S = 20 \Omega$		18		nV/√Hz
I _n	Equivalent input noise current	f = 1 kHz		0.01		pA/√Hz



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LF347BD	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF347BDR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF347BN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
LF347D	ACTIVE	SOIC	D	14	50	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF347DR	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR
LF347N	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



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